

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (currently amended) A package for containing an electronic circuit assembly, the package comprising:

- a) a housing having a bottom surface and a plurality of walls extending upwardly from the bottom surface, the walls and the bottom surface defining a cavity in the housing, the cavity being adapted to hold the electronic circuit assembly;
- b) at least one post extending outwardly from one of the walls, the post being integrally formed with the housing, the post having a first end and a second end, the first end connected to the wall;
- c) a threaded annular sleeve portion located at the second end of the post, the threaded annular sleeve portion adapted to receive a female connector portion;
- d) a bore passing through the post and the wall, the bore adapted to receive a feed through terminal, the feed through terminal having a pin located on one end and a receptacle located on another end; ~~and~~
- ~~e) a cover located over the cavity and attached to the housing;~~
- e) an insulator located in the bore surrounding the feed through terminal;
- f) at least one groove located in the bottom surface of the housing;
- g) a reflowed solder paste contained within the groove, the reflowed solder paste electrically connecting the electronic assembly to the housing; and
- h) a cover mounted over the cavity and connected to the housing.

2. (canceled)

3. (currently amended) The package according to claim 1, wherein the ~~terminal~~ pin is soldered to the electronic circuit assembly.

4. (original) The package according to claim 1, wherein the electronic circuit assembly is a printed circuit board.

5. (original) The package according to claim 1, wherein the housing and cover are formed from metal.

6. (canceled).

7. (original) The package according to claim 1, wherein the housing and cover are connected together by a fastener.

8. (currently amended) A electronic enclosure for containing an electronic circuit assembly comprising:

- a) a housing having a bottom surface and a plurality of walls extending upwardly from the bottom surface, the walls having an inner wall surface and an outer wall surface, the inner wall surfaces and the bottom surface defining a cavity in the housing, the cavity being adapted to hold the electronic circuit assembly;
- b) a plurality of posts extending perpendicularly from the outer wall surfaces, each post having a first end and a second end, the first end of the post connected to the outer wall surface;
- c) a threaded annular sleeve portion surrounding the post and located toward the second end, the threaded annular sleeve portion adapted to receive a female connector portion;
- d) a bore extending from the inner wall surface through the wall, the post and terminating at the second end;
- e) a feed through terminal located in the bore, the feed through terminal including a pin surrounded by an insulator;
- f) a groove located in the bottom surface;
- g) a printed circuit board mounted in the cavity, the printed circuit board having a top surface and a metallized bottom surface, the metallized bottom surface located adjacent the groove;
- h) a solder connection located within the groove between the bottom surface of the housing and the metallized bottom surface of the printed circuit board; and

i) If a cover located over the cavity and attached to the housing.

9. (canceled).

10. (currently amended) The package according to claim 8, wherein the feed-through terminal is soldered to the electronic circuit assembly pin is soldered to the top surface of the printed circuit board.

11. (canceled).

12. (original) The package according to claim 8, wherein the housing and posts are formed from a single piece of material.

13. (original) The package according to claim 12, wherein the single piece of material is metal.

14. (original) The package according to claim 12, wherein the single piece of material is machined to form the housing and posts.

15. (original) The package according to claim 8, wherein the cover is L-shaped and extends over the cavity and one of the walls.

16-18. (canceled).

19. (new) A method of making an electronic package, the method comprising:

- a) providing a housing having a bottom surface and a plurality of walls extending upwardly from the bottom surface, the walls and the bottom surface defining a cavity, the housing having a plurality of posts extending from the wall, the post having a threaded sleeve portion and a bore extending through the post, the bottom surface having a groove;
- b) providing a printed circuit board having a circuitized top surface and a metallized bottom surface;
- c) dispensing a solder paste into the groove;
- d) placing the printed circuit board into the cavity and over the groove such that the metallized bottom surface is in contact with the solder paste;
- e) reflowing the solder paste such that an electrical contact is formed between the housing and the metallized bottom surface;
- f) inserting a feed through terminal into the bore, the feed through terminal having a pin end and a receptacle end;
- g) soldering the pin end to the circuitized top surface;
- h) placing a cover over the cavity; and
- i) attaching the cover to the housing.